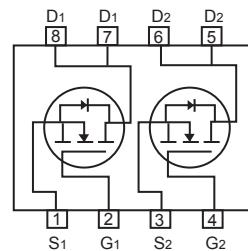
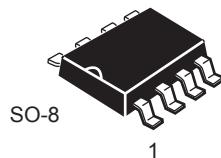


## FEATURES

- 30V, 7.6A,  $R_{DS(ON)} = 22m\Omega$  @ $V_{GS} = 10V$ .  
 $R_{DS(ON)} = 33m\Omega$  @ $V_{GS} = 4.5V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- Lead free product is acquired.
- Surface mount Package.

ABSOLUTE MAXIMUM RATINGS  $T_A = 25^\circ C$  unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	7.6	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	30	A
Maximum Power Dissipation	$P_D$	2.0	W

## Thermal Characteristics

Parameter	Symbol		
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	62.5	°C/W



CEM3178

**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
<b>On Characteristics</b> <sup>c</sup>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 6.3\text{A}$		17	22	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 5.0\text{A}$		27	33	$\text{m}\Omega$
<b>Dynamic Characteristics</b> <sup>d</sup>						
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = 15\text{V}, I_D = 6\text{A}$		5		S
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		590		pF
Output Capacitance	$C_{\text{oss}}$			125		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			95		pF
<b>Switching Characteristics</b> <sup>d</sup>						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 15\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		10	20	ns
Turn-On Rise Time	$t_r$			4	8	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			25	50	ns
Turn-Off Fall Time	$t_f$			4	8	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 15\text{V}, I_D = 6\text{A}, V_{\text{GS}} = 5\text{V}$		13	17	nC
Gate-Source Charge	$Q_{\text{gs}}$			2		nC
Gate-Drain Charge	$Q_{\text{gd}}$			3.5		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				1.6	A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 1.6\text{A}$			1.2	V

## Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Surface Mounted on FR4 Board,  $t \leq 10 \text{ sec.}$
- c.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- d.Guaranteed by design, not subject to production testing.

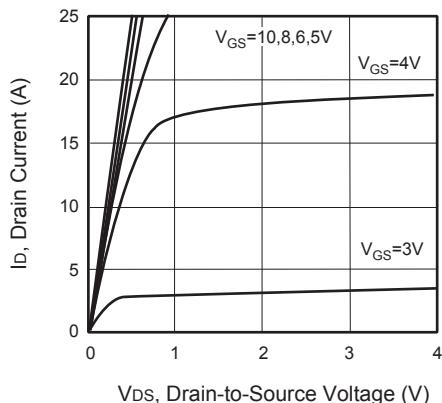


Figure 1. Output Characteristics

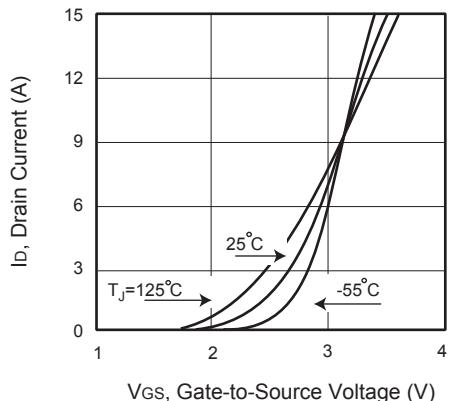


Figure 2. Transfer Characteristics

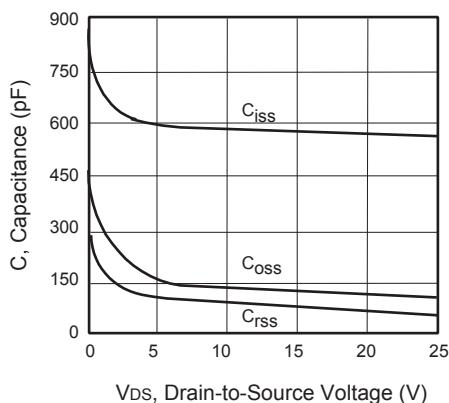


Figure 3. Capacitance

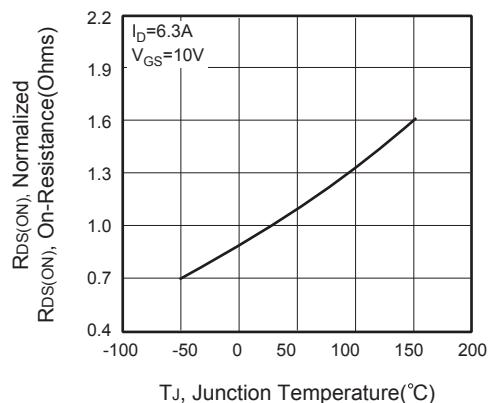


Figure 4. On-Resistance Variation with Temperature



Figure 5. Gate Threshold Variation with Temperature

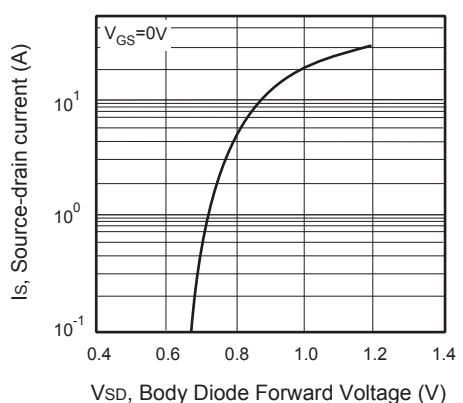
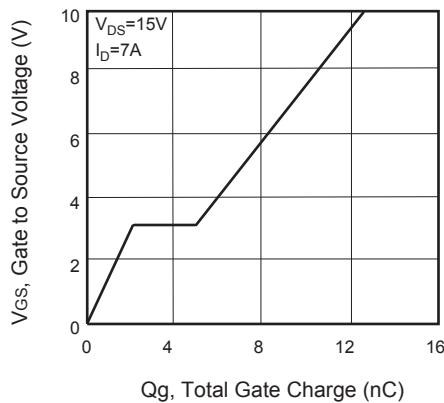
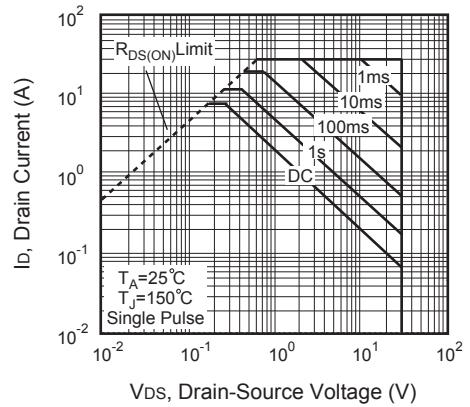


Figure 6. Body Diode Forward Voltage Variation with Source Current



**Figure 7. Gate Charge**



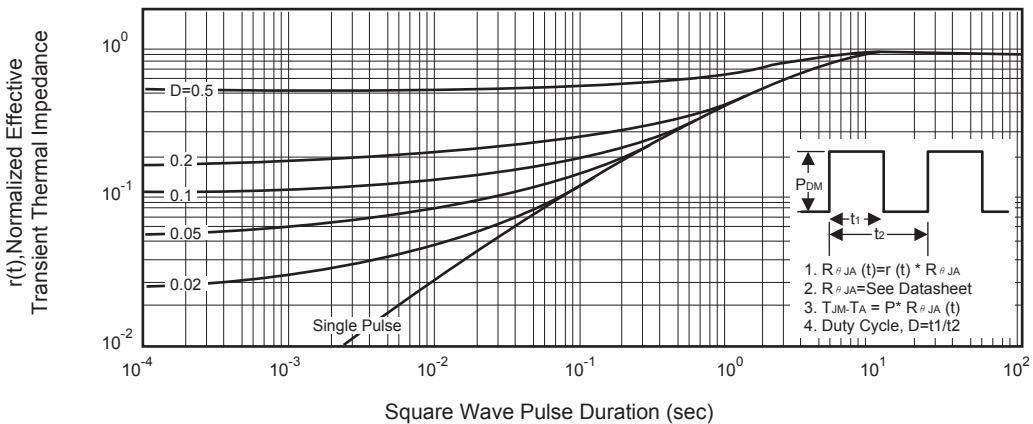
**Figure 8. Maximum Safe Operating Area**



**Figure 9. Switching Test Circuit**



**Figure 10. Switching Waveforms**



**Figure 11. Normalized Thermal Transient Impedance Curve**